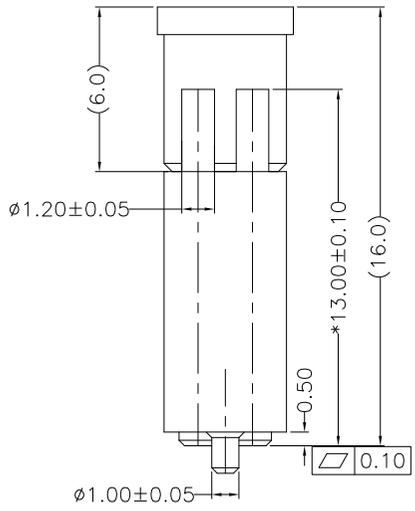
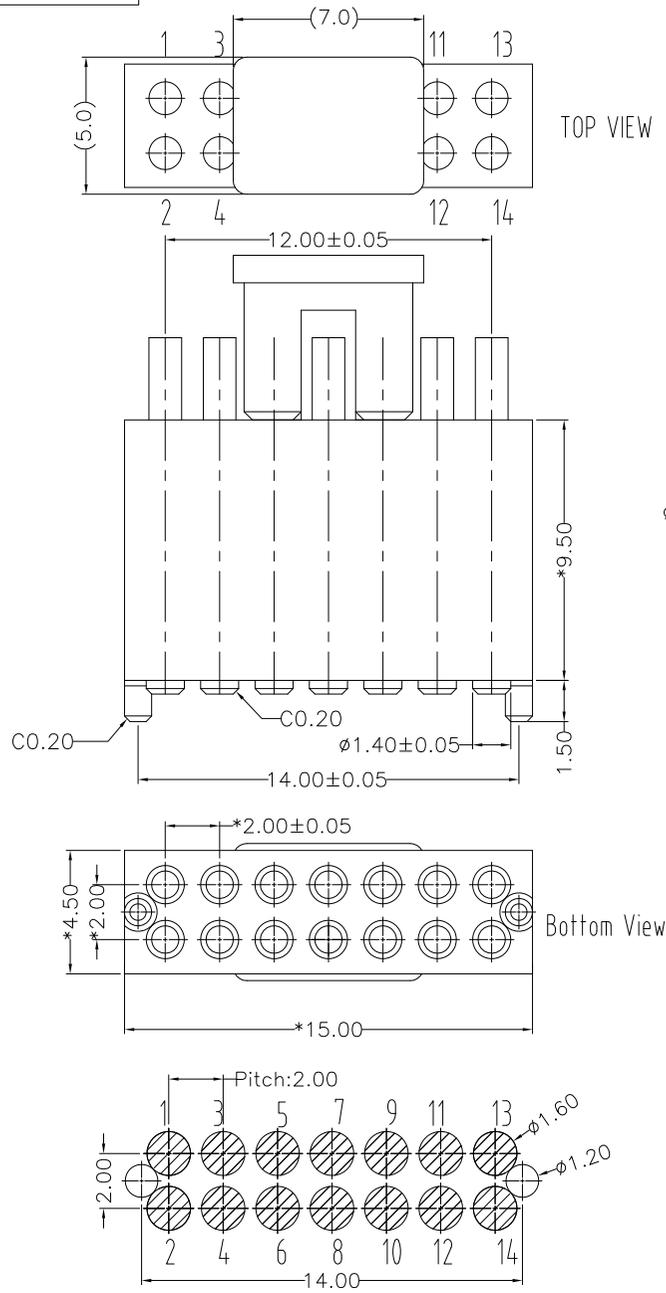


# GP Component

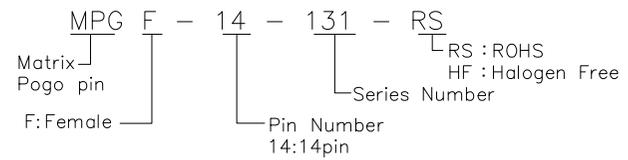
REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2023/09/14	Hanson
A1			Add engraving words	2024/06/05	Wu Zonlin
A1.1			Add font	2024/06/06	Wu Zonlin



**Notes:**

- Material**  
 Pin: Lead free Brass ,Plated Gold flash(1u~min.)  
 over 50-120u~Ni  
 Housing:PA9T Black UL94 v-0
- Electrical**  
 Rated Current&Voltage: DC 12V, 2.0A  
 Contact Resistance: 100mohm max.
- Operating Temperature: -40 to +85°C**  
 Humidity Range:10%RH to 90%RH  
 Solder Temperature: 260°C±5° 10s±2s  
 Salt Spray:24H, No Corrosion  
 Lead free ,RoHS compliant
- Packing:Reel&Carrier**
- "\*"is the key dimensions .**

**MATRIX PART NO:**



**RECOMMENDED PCB LAYOUT**  
 Tolerance: ±0.05mm

 <b>Matrix Electronics Co., Ltd</b>				
TOLERANCE: 0~6.0 ±0.10mm >6~30 ±0.20mm >30~120 ±0.30mm >120 ±0.50mm ANGLE: ±5°	DESIGN BY : Wu Zonlin	DATE : 2024/06/06	PART NAME: Pogopin conn	
 UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY: Hanson Huang	DATE : 2024/06/06	PART NO.	MPGF-14-131-RS
	APPROVED BY1: Richard Hsieh	DATE : 2024/06/06	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2024/06/06	DRAW NO.	
			SHEET NO.	1 OF 1